

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	25	((TATSUO) near2 (KATAOKA)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:31
S2	6	((YOSHIKAZU) near2 (AKASHI)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:32
S4	38	S1 S2 S3	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/29 15:33
S3	17	((YUTAKA) near2 (IGUCHI)). INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:33
S5	1	(process or method) board (insulating adj (film or layer)) (conductive near1 layer) (sputtered adj metal adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:41
S6	2	(process or method) board (insulating adj (film or layer)) (conductive near1 layer) (sputtered adj metal adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:42
S8	7	("6824827" "6613987" "4742009" "5227224" "5130192" "5998739" "5044073").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/29 15:48
S9	0	("2007/0145584").URPN.	USPAT	AND	ON	2008/01/29 15:49
S10	2	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or layer)) etch\$3 ((etch\$3 or dissolv \$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 16:32

S11	13	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or layer)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:44
S12	13	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or plane or plate or layer)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:45
S14	2	S11 S13	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:54
S13	132	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) etch\$3 ((etch \$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:54
S15	20	S13 sputtered	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 15:13
S16	13	S12 (sputtered adj metal adj (film or plane or plate or layer))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:06
S17	6	S12 (sputtered adj metal adj (layer))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:09
S20	0	S13 S18	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:26
S18	48	(US-5480730-\$ or US-5364707-\$ or US-6060175-\$ or US-5199163-\$ or US-5326643-\$ or US-4341942-\$ or US-4780957-\$ or US-4830691-\$ or US-4968398-\$ or US-4976808-\$ or US-5200026-\$ or US-5231751-\$ or US-5442145-\$ or US-5569739-\$ or US-5582858-\$ or US-5599582-\$ or US-5621246-\$ or US-5628852-\$ or US-5686702-\$ or US-5736681-\$ or US-5858518-\$ or US-5865934-\$ or US-5889325-\$ or US-6096482-\$ or US-6100582-\$ or US-6124004-\$).did. or (US-6165629-\$ or US-6190493-\$	USPAT	AND	ON	2008/01/30 16:26

		or US-6214923-\$ or US-6228511-\$ or US-6245432-\$ or US-4347306-\$ or US-4353954-\$ or US-4411982-\$ or US-4592801-\$ or US-4882216-\$ or US-4907039-\$ or US-4982265-\$ or US-5019944-\$ or US-5224265-\$ or US-5232548-\$ or US-5246564-\$ or US-5266446-\$ or US-5359222-\$ or US-5373627-\$ or US-5587341-\$ or US-5589668-\$ or US-5659198-\$).did.				
S21	495	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputter\$3 near2 metal) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:27
S22	0	S18 S21	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:28
S23	27	(process or method) board (insulating adj film) (conductive adj layer) etch \$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:37
S24	0	(process or method) board (insulating adj film) (conductive adj layer) etch \$3 (sputtered adj metal adj layer)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:38
S26	0	S23 S25	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:39
S25	33	board (conductive adj layer) (sputtered adj metal adj layer)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:39
S27	18	(process or method) board (insulating adj film) (conductive adj layer) etch \$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome)) sputter\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:40
S28	1	(process or method) board (insulating adj (film or layer)) (conductive near1 layer) (sputtered adj metal adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:34

S31	18	((etch\$3 or dissolv\$3) near2 (nickel and chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:35
S30	1	(process or method) board (insulating adj (film or layer)) ((etch\$3 or dissolv \$3) near2 (nickel and chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:35
S29	1	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) etch\$3 ((etch \$3 or dissolv\$3) near2 (nickel and chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:35
S32	15	(process or method) board ((insulating or polyimide) adj film) (conductive adj layer) etch\$3 (sputtered adj metal adj layer)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:46
S33	2	(process or method) board ((liquid or wet) near3 (etch \$3 or dissolv\$3)) ((etch\$3 or dissolv\$3) near3 nickel) ((etch\$3 or dissolv\$3) near3 chrome)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:30
S34	5	((liquid or wet) with (etch\$3 or dissolv\$3)) ((etch\$3 or dissolv\$3) near2 nickel) ((etch\$3 or dissolv\$3) near2 chrome)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:33
S36	1	S35 (remove with (residual with surface))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:52
S35	22	(US-20060048963-\$ or US-20070037379-\$ or US-20050258522-\$ or US-20050181542-\$ or US-20020148733-\$ or US-20030142453-\$ or US-20050189136-\$ or US-20010036052-\$ or US-20040099374-\$ or US-20050003673-\$).did. or (US-6824827-\$ or US-5998739-\$ or US-5227224-\$ or US-5130192-\$ or US-5044073-\$ or US-4742009-\$ or US-6613987-\$ or US-6900110-\$ or US-6867073-\$ or US-4921777-\$ or US-6071597-\$ or US-4874483-\$).did.	US-PGPUB; USPAT	AND	ON	2008/01/31 09:52

S37	3	S35 (residual with surface)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:59
S38	16	(depth near2 (polyimide adj film)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 11:23
S39	1	(sputtered adj metal adj layer) with ((nickel or Ni) and (chrome or chromium))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 12:16
S40	91	(sputtered near2 layer) with ((nickel or Ni) and (chrome or chromium))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 12:17
S41	62946	(plat\$3 near3 (copper or (copper adj alloy)))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 13:21
S42	19	S40 S41	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 13:22
S43	2	("2004/0231141").URPN.	USPAT	AND	ON	2008/01/31 14:12
S45	21	S44 (sputter\$3 with copper)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 14:36
S44	42	(US-20060048963-\$ or US- 20070037379-\$ or US- 20050258522-\$ or US- 20050181542-\$ or US- 20020148733-\$ or US- 20030142453-\$ or US- 20050189136-\$ or US- 20010036052-\$ or US- 20040099374-\$ or US- 20050003673-\$ or US- 20020009820-\$ or US- 20020061424-\$ or US- 20030031877-\$ or US- 20030132823-\$ or US- 20030198828-\$ or US- 20030198836-\$ or US- 20030222668-\$ or US- 20040231141-\$ or US- 20050051872-\$ or US- 20050098433-\$ or US- 20030134273-\$ or US- 20030210496-\$).did. or (US- 6824827-\$ or US-5998739-\$ or US-5227224-\$ or US- 5130192-\$ or US-5044073-\$ or US-4742009-\$ or US- 6613987-\$ or US-6900110-\$ or US-6867073-\$ or US- 4921777-\$ or US-6071597-\$	US-PGPUB; USPAT	AND	ON	2008/01/31 14:36

		or US-4874483-\$ or US-4077854-\$ or US-4582559-\$ or US-4942373-\$ or US-5058250-\$ or US-5099120-\$ or US-5179188-\$ or US-6143427-\$ or US-6689476-\$).did.				
S46	7	S44 (plating near3 pattern)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 14:51
S47	1	S44 (plating near3 (wiring adj pattern))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 14:52
S48	1	"20050003673".did.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:17
S50	2	("20020148733" "20050258522").did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/31 15:22
S49	0	("20020148733" "20050258522").did.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:22
S51	1705	174/254-258.cor. 361/792-795.cor.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/31 15:31
S53	7	S51 S52	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:32
S52	132	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) etch\$3 ((etch \$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:32
S56	1	S51 S55	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:33
S55	13	S54 (sputtered adj metal adj (film or plane or plate or layer))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:33
S54	13	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or plane or plate or layer)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:33
L1	5	(@AD<"20031205") (((sulfuric hydrochloric) adj acid) with "%" with (C or drgree) with second)	US-PGPUB; USPAT	AND	ON	2008/07/12 15:07

L2	0	(@AD<"20031205") ((aqueous adj potassium adj permanganate adj KOH) with "g/l" with (C or dgree) with second)	US-PGPUB; USPAT	AND	ON	2008/07/12 15:09
L3	0	(@AD<"20031205") ((aqueous adj potassium adj permanganate adj KOH) with concentration with (C or dgree) with second)	US-PGPUB; USPAT	AND	ON	2008/07/12 15:10
L4	0	(@AD<"20031205") ((aqueous adj potassium) with concentration with (C or dgree) with second) permanganate KOH	US-PGPUB; USPAT	AND	ON	2008/07/12 15:11
L5	0	(@AD<"20031205") ((aqueous adj potassium) with (C or dgree) with second) permanganate concentration KOH	US-PGPUB; USPAT	AND	ON	2008/07/12 15:12
L7	0	1 6	US-PGPUB; USPAT	AND	ON	2008/07/12 15:16
L6	343	(@AD<"20031205") aqueous potassium ((C or dgree) with second) permanganate concentration KOH	US-PGPUB; USPAT	AND	ON	2008/07/12 15:16
L10	9	(US-20050003673-\$ or US- 20020148733-\$ or US- 20050258522-\$).did. or (US- 5130192-\$ or US-5044073-\$ or US-6071597-\$ or US- 6620306-\$ or US-6877428-\$ or US-5334314-\$).did.	US-PGPUB; USPAT	AND	ON	2008/07/12 16:28

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